

GBU6005 THRU GBU610

GLASS PASSIVATED BRIDGE RECTIFIER

Reverse Voltage - 50 to 1000 Volts Forward Current - 6.0 Ampere

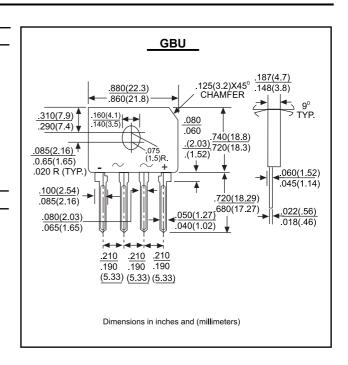
FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capability

MECHANICAL DATA

- Case:Molded plastic, GBU
- Terminals: Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	Symbols	GBU 6005	GBU 601	GBU 602	GBU 604	GBU 606	GBU 608	GBU 610	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current with Heatsink at T _C = 100 °C	I _(AV)	6.0							А
Peak Forward Surge Current, 8.3 ms Single Half-Sine -Wave superimposed on rated load (JEDEC Method)	I _{FSM}	175							Α
Maximum Forward Voltage at 3.0 A DC and 25 °C	V _F	1.0							V
Maximum Reverse Current at T _A = 25 °C at Rated DC Blocking Voltage T _A = 125 °C	I _R	10.0 500							μА
Typical Junction Capacitance 1)	CJ	50							pF
Typical Thermal Resistance 2)	$R_{\theta JC}$	2.2							°C/W
Operating and Storage Temperature Range	T_J,T_S	-55 to +150							°C

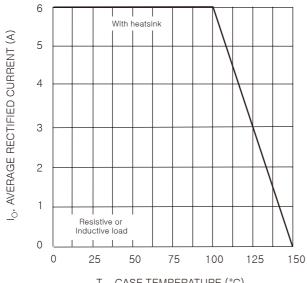
¹⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

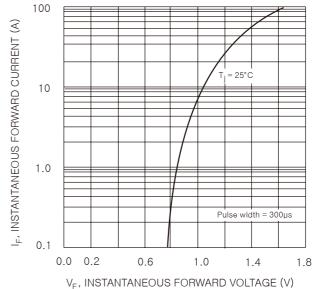
²⁾ Thermal resistance from junction to case with device mounted on 300 mm X 300 mm X 1.6 mm Cu plate heatsink.



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RATINGS AND CHARACTERISTIC CURVES





 T_{C} , CASE TEMPERATURE (°C) V_{F} , INSTANTANEOUS FORWARD VOLFig. 1 Forward Current Derating Curve Fig. 2 Typical Forward Characteristics

